



PowerPAD™ HSSOP - 2.475 mm max height

[illegible]

PowerPAD is a trademark of Texas Instruments.

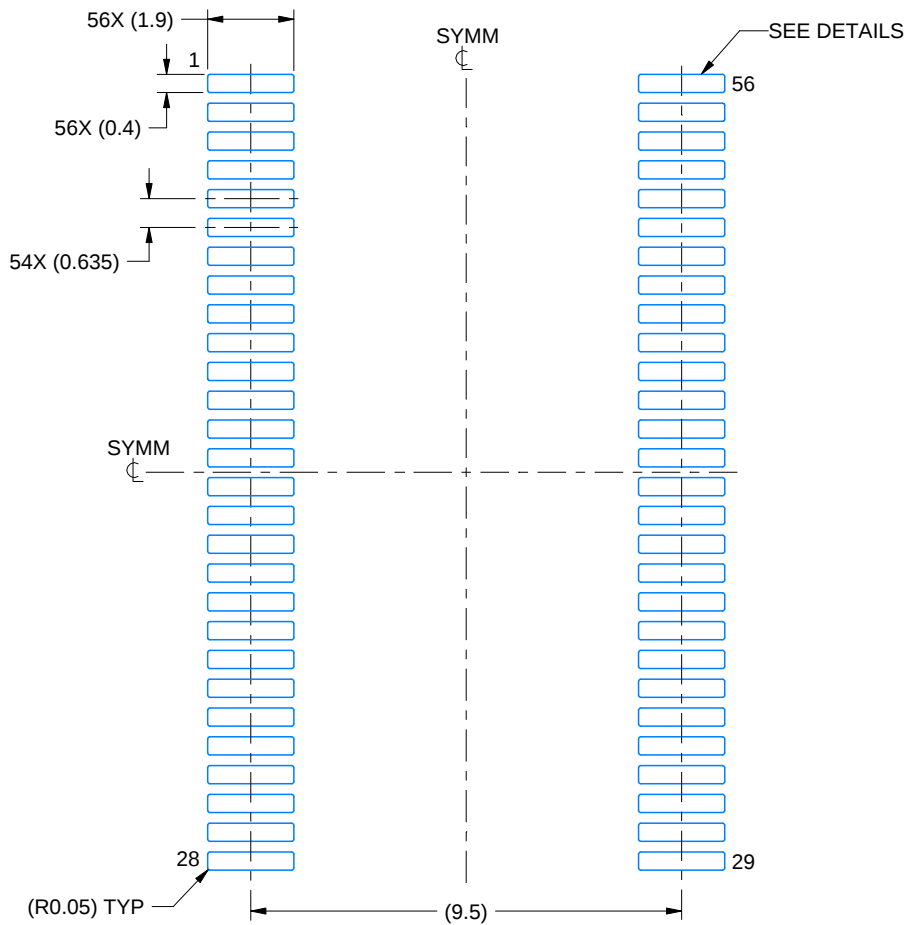
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EXAMPLE BOARD LAYOUT

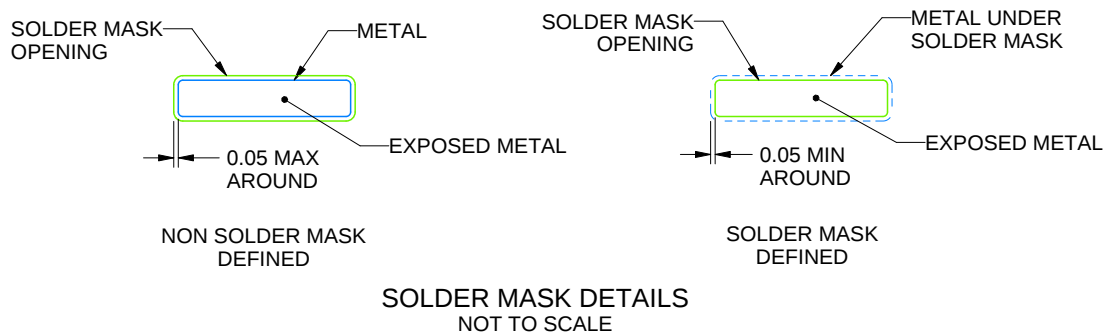
DKQ0056C

PowerPAD™ HSSOP - 2.475 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:6X



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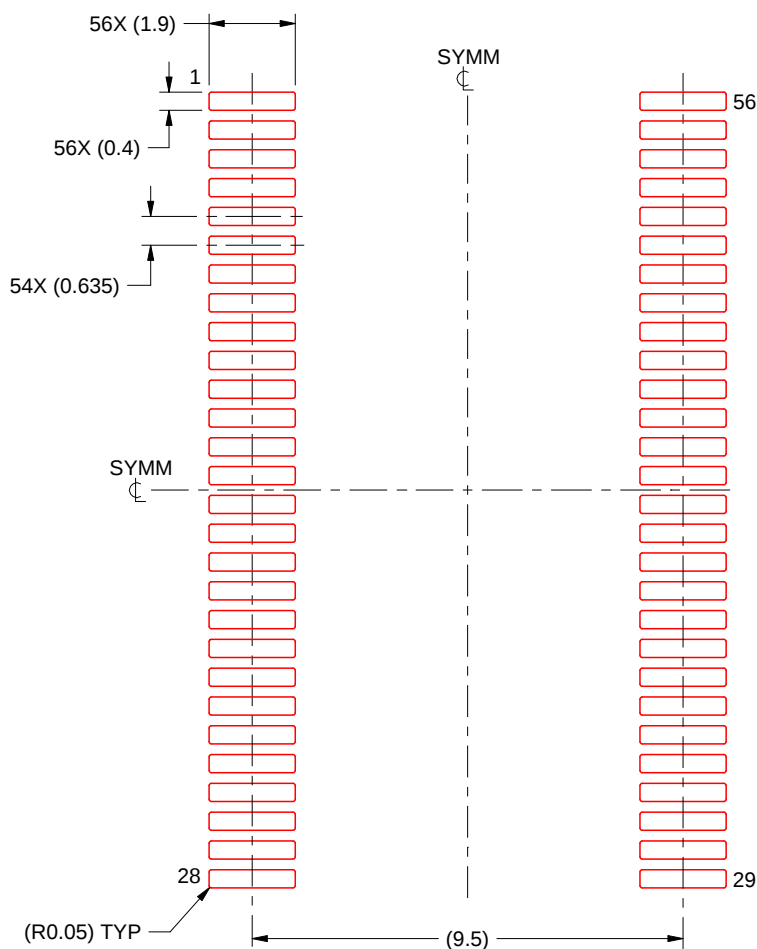
NOTES: (continued)

7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
9. Size of metal pad may vary due to creepage requirement.

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PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE:6X

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NOTES: (continued)

10. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
11. Board assembly site may have different recommendations for stencil design.